

OPEN

Compute Project

1 **Hardware Management**

2 **ICAP DRAM**

3 Version 0.03

4 **Draft**

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6 1 Scope

7 This document defines the technical specifications identifying DRAM slots and
8 modules used in Open Compute Project servers, storage devices and network
9 switches. The specification is limited to the data format and commands defined in
10 Intelligent Platform Management Interface specification and does not require the
11 presence of an operating system on the device that is managed.

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31 Revision History

Date	Revision	Description
February 11, 2014	0.02	Initial revision. Added content from document "Type A IPM Controllers"
June 9, 2014	0.03	Added Section OCP Specification Identification.

32 2 Overview

33 This describes the Intelligent Platform Management Interface (IPMI) capabilities(ICAP)
 34 implemented by an IPM Controller. It extends the IPMI 2.0 specification allowing Data
 35 Centers System Managers to implements a uniform identification and monitoring of
 36 DDR3 and DDR4 modules used in servers, storage devices and network switches.

37 This specification is one in a series of IPM Controller Capabilities(ICAP) which add
 38 functionality not found in the IPMI 2.0 specification.

39 This specification does not contain any requirements for hardware dimensions,
 40 connectors or electrical interfaces.

41 2.1 License

42 As of April 7, 2011, the following persons or entities have made this Specification
 43 available under the Open Web Foundation Final Specification Agreement (OWFa 1.0),
 44 which is available at [http://www.openwebfoundation.org/legal/the-owf-1-0-
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 48 for this Specification at <http://opencompute.org/licensing/>, which may also include
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 59 SPECIFICATION OR ITS GOVERNING AGREEMENT, WHETHER BASED ON BREACH OF
 60 CONTRACT, TORT (INCLUDING NEGLIGENCE), OR OTHERWISE, AND WHETHER OR NOT
 61 THE OTHER PARTY HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.

62 2.2 Reference Documents

63 These documents are referenced by this specification.

64 2.2.1 Specification Documents

Acronym	Date	Specification
DDR3 SPD	9/1/2011	JEDEC Standard No. 21-C, Annex K: Serial Presence Detect (SPD) for DDR3 SDRAM Modules, Release 4
DDR4 SPD	November 2013	JEDEC Standard No. 21-C Release 23, Annex L: Serial Presence Detect (SPD) for DDR4 SDRAM Modules

Acronym	Date	Specification
DDR Thermal Sensor	November 2009	JEDEC Standard No. 21-C Release 19, Section 4.1.5 TS3000 Standalone Thermal Sensor Component
IPMI 2.0	10/1/2013	Intelligent Platform Management Interface Specification Second Generation v2.0, Document Revision 1.1

65 2.3 Keywords

66 **shall**

67 A keyword indicating a mandatory requirement; designers are required to implement
68 all such mandatory requirements to ensure interoperability with other products that
69 conform to this specification.

70 **shall not**

71 A keyword used to describe a feature, function, or coded value that is defined in a
72 specification to which this specification makes a normative reference where the use
73 of said feature, function, or coded value is not allowed for implementations of this
74 specification.

75 2.4 Out of Scope

76 This specification does not contain any requirements for hardware dimensions or
77 connectors .

78 Ethernet connection or the TCP/UDP protocol is not required to implement this
79 specification.

80 The electrical interface between the IPM Controller and any device is not defined in
81 this document.

82 Hot plug DDR memory modules are not supported.

83 2.5 Private Enterprise Number

84 The IPMI Commands and FRU records defined in this document utilize the Private
85 Enterprise Number 42623 assigned to OCP by the Internet Assigned Number
86 Authority , www.iana.org. In a twist of fate that only a IPMI implementer will enjoy,
87 the number assigned to OCP ends in the IPMI UDP port number, 623.

88 2.6 OCP Specification Identification

89 This specification is identified by five fields defined in the OCP document Hardware
90 Management SPEC ID. The five field are present in Table 2, OCP Specification
91 Descriptor byte offsets zero to five and Table 4, Get OCP Specification Version byte
92 offsets one to six. The value of the five fields are found in the following requirements.

IPMA-IPM-2.1 The *OCP Specification ID* used to identify any revision of this document
shall be a value of 0x2.

IPMA-IPM-2.2 The *OCP Specification Revision* used to identify this specific document **shall** be a value of 0x0.

93 2.7 FRU Records

94 All FRU records defined in this specification contain the Private Enterprise Number as
95 the first three bytes after the record header checksum and is written Least Significant
96 byte first.

97 3 DRAM Management

98 This specification is part of the IPMI Capabilities(ICAP) Identification and Status(IDS)
99 series providing a uniform interface for managing servers, storage devices or network
100 switches. ICAP enables a Data Center System Manager to control rack mounted
101 hardware with minimum operator intervention. The ICAP specifications allow a single
102 technician to operate 10,000 to 50,000 servers.

103 The IDS set of specifications allow the physical location of a device in a two
104 dimensional grid and provide status information which includes sensors for device
105 present/absent, temperature and voltage.

106 This document, identified by acronym ICAP-DRAM, defines set of requirements for an
107 IPM Controller implementing the Intelligent Platform Management Interface (IPMI 2.0)
108 to monitor DDR3 and DDR4 modules on Servers, Storage Devices and Network
109 Switches, which this document collectively calls IT hardware. No distinction is made
110 between the different types of IT hardware. The benefits to the Data Center operator
111 are a uniform, vendor and hardware neutral methods for:

- 112 • inventory data collection of DDR3/DDR4 manufacturer id, model, serial
113 numbers
- 114 • on-site customer acceptance tests validating server memory size
- 115 • System Manager error messages identifying the specific DRAM slot
- 116 • identification of empty DRAM slots so servers can be upgraded
- 117 • identification of DDR3/DDR4 memory capacity and module errors
- 118 • report temperature alarms on DDR3/DDR4 modules

119 The requirements in this document are specific to IPM Controllers in IT hardware and
120 no requirements are made on the System Manager itself. If a System Manager is not
121 present, the IT Hardware will function normally.

122 This specification is not mandatory for IT Hardware. There is no architectural
123 limitation preventing a single chassis from containing IPM Controllers implementing
124 this specification and IPM Controllers implementing proprietary IPM Controllers.

125 DDR3 and DDR4 memory modules which may be removable or be soldered to a PCB.
126 The FRU Information Records have been designed so DDR3/DDR4 memory modules
127 that are soldered to a board can be coexist with removable memory that on the same
128 circuit board. This allows a System Manager to determine the correct amount of
129 memory when a single CPU uses low cost soldered DDR memory modules and the
130 higher cost removable modules.

131 3.1 Inventory

132 An IPM Controller allows IT hardware a common interface to identify the location and
133 inventory of memory modules supported by the main CPUs. A System Manager
134 query the IPM Controller to determine what type of memory modules, if any, are
135 installed in the memory module slots. This allows a System Manager to maintain a
136 real time database of the type, memory capacity of each memory module and the
137 total installed memory capacity available to each CPU.

138 This allows a System Manager to:

- 139
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1. detect failed or incorrectly seated memory modules. The System Manager's database contains the expected number of modules in server and can detect if the actual number is lower.

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 2. detect which servers can be upgraded to higher memory capacity by populating unused slots or replacing low capacity modules with higher capacity modules.

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 3. compare memory module thermal design parameters to choose lowest cost cooling solutions. For example a Data Center may find it more cost effective to replace 85° C maximum operating temperate memory modules with 95° C modules than to redesign air conditioning systems.

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 4. select hardware based on actual memory capacity to install operating systems and the applications.

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 5. predict the number of memory modules which can be reallocated to other IT hardware when permanently deactivating running systems. For example when RAID is going to be removed from the Data Center how many DDR3 modules can be reallocated to compute servers.

155 3.2 Monitoring

156 One goal of the ICAP specifications is to provide Data Center operators information on
157 how close the IT hardware is the operating limits. This information is valuable when
158 raising air temperature in a data hall in an effort to decrease operating costs.

159 DDR3 memory modules rated at 95° C are required to have temperature sensors. The
160 sensors are optional for 85° C modules.

161 A System Manger communicating with a IPM Controller implementing ICAP-DRAM(this
162 specification) can determine, when a memory module is withing the vendor defined
163 temperature envelope.

164 4 Memory Module Slots

165 A location where a memory module may be present is called a slot. It may be a card
166 edge connector or a slot is memory soldered to a printed circuit board.

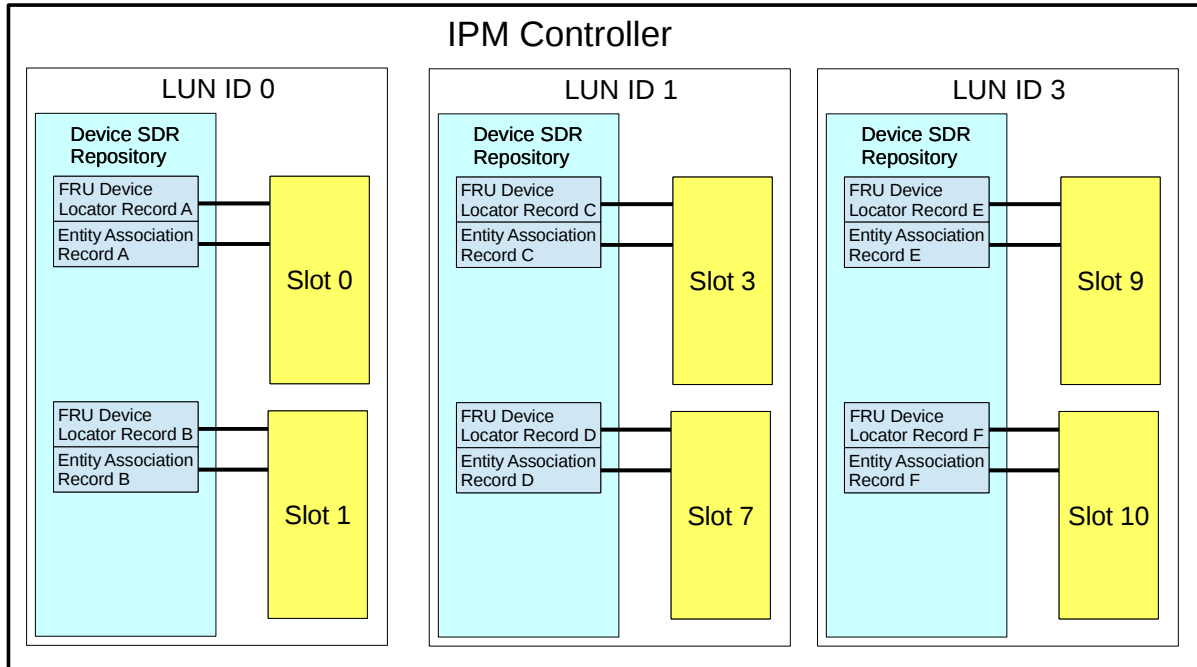
167 This specification is not designed to allow memory module slots or memory modules
168 to be inserted or removed while an IPM Controller is operating.

169 4.1 Logical Slot Identification

170 An IPM Controller identifies the memory module slots associated with the main
171 CPU(s) with an IPMI FRU Device Locator Record. It identifies the FRU address that
172 represents the memory module slot. The *Device ID* Field contains the ASCII
173 characters that uniquely identify the slot either in manufacturer documentation or
174 the characters are printed on the circuit board adjacent to the memory slot. This
175 allows a System Manager to create error messages that are specific to a memory
176 module slot.

177 Each LUN ID has a separate Device SDR repository. A single Device SDR Repository
178 contains all bays FRU Device Locator Records that are managed by the LUN ID. There
179 are a maximum of four LUN IDs within an IPM Controller.

1 **Illustration 1: IPMC to Device SDR Repository Mapping**



180 Each memory module slot's FRU Device Locator record contains an Entity ID Instance

181 Number that is unique from all other memory module slots' FRU Device Locator
182 records within the same Device SDR Repository.

- DRAM-SLO-4.1 Each DDR3 or DDR4 memory module slot shall have IPMI FRU Device Locator Record present in the Device SDR Repository present in the same LUN ID as found in the FRU Device Locator Record *Logical-Physical / Access LUN / Bus ID* Field(byte8) bits 4:3.
- DRAM-SLO-4.2 Each IPMI FRU Device Locator Record for a memory module slot **shall** have the Fru Entity ID field(byte 13) set to 8h.
- DRAM-SLO-4.3 If the memory slot is for a DDR3 module the FRU Device Locator Record for a memory module slot **shall** have the *Device Type* field(byte 11) set to a value to C0h(Table 3: IPMB/I2C Device Type Codes).
- DRAM-SLO-4.4 If the memory slot is for a DDR3 module the FRU Device Locator Record for a memory module slot **shall** have the *Device Type Modifier* field(byte 12) set to a value to C0h(Table 3: IPMB/I2C Device Type Codes).
- DRAM-SLO-4.5 If the memory slot is for a DDR4 module the FRU Device Locator Record for a memory module slot **shall** have the *Device Type* field(byte 11) set to a value to C1h(Table 3: IPMB/I2C Device Type Codes).
- DRAM-SLO-4.6 If the memory slot is for a DDR4 module the FRU Device Locator Record for a memory module slot **shall** have the *Device Type Modifier* field(byte 12) set to a value to C1h(Table 3: IPMB/I2C Device Type Codes).
- DRAM-SLO-4.7 All FRU Device Locator Record for a memory module slot **shall** have an unique combination of IPMI Channel, IPMB address, LUN ID and FRU ID.
- DRAM-SLO-4.8 No Device Locator Records for a memory module slot **shall** have an identical value in the *FRU Entity Instance* field.
- DRAM-SLO-4.9 All Compact and Full Sensor Records for the memory module **shall** be present in the same LUN ID's Device SDR Repository containing the memory module slot's FRU Device Locator Record.

183 4.1.1 Physical Slot Identification

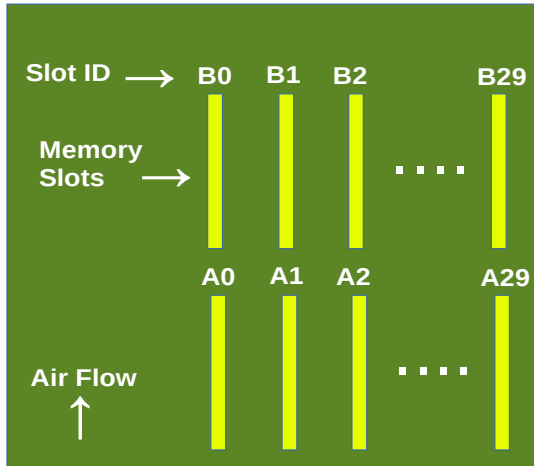
184 Memory slots are identified with two or three characters. The identification is called a
185 Slot ID. Slot IDs may appear on the printed circuit board, documentation or in
186 System Manager error messages.

187 The leading character of a Slot ID is an uppercase letter indicating the row number
188 assigned to the memory slot. Rows are assigned sequentially increasing alphabetic
189 characters. The first row is always "A" and is closest to the air inlet.

190 The trailing characters are a numeric value from 0 to 29 indicating the column
191 number assigned to the memory slot. Columns are assigned from left to right.
192 Columns are sequentially assigned a number with no numeric gaps allowed.

193 There is always a memory Slot ID A0.

Illustration 2: Example Memory Slot ID Layout



- DRAM-SLO-4.10 An IPMI FRU Device Locator Record for a memory module slot **shall** have a unique *Device String* compared with all other memory module FRU Device Locator Records within the same Device SDR Repository.
- DRAM-SLO-4.11 The first character in the FRU Device Locator Record Field *Device String* **shall** be an upper case letter indicating the row containing the memory slot.
- DRAM-SLO-4.12 The second and third character in the FRU Device Locator Record Field *Device String* **shall** be a numeric indicating the column containing the memory slot.
- DRAM-SLO-4.13 The maximum length of the Device Locator Record Field *Device String* **shall** be three ASCII characters.
- DRAM-SLO-4.14 If the column number of the memory slot is less than ten the length of the Device Locator Record Field *Device String* **shall** be two ASCII characters.
- DRAM-SLO-4.15 The IPM Controller **shall** identify memory slot column from left to right with a digit with the left most digit being zero.
- DRAM-SLO-4.16 The IPM Controller **shall** identify the left most memory slot column as digit zero.
- DRAM-SLO-4.17 The IPM Controller **shall** identify the memory slot row closest to the air intake with the upper case letter A.

194 **4.2 Slot Sensors**

195 Memory modules can not be inserted and removed while the IT hardware is running.
 196 The IPM Controller is responsible detecting optical modules when the IPM Controller is
 197 reset or powered on. It generates sensor SDR records and inserts them in the Device
 198 SDR repository.

- OPTI-BAY-4.18 The IPM Controller **shall** detect the memory modules when it is powered on or reset.

199 The Entity Instance number present in the FRU Device Locator Record for a single
 200 memory module bay is identical for all Compact and Full Sensor Records related to a
 201 single memory module slot and it's memory module.

202 4.2.1 Module Presence Sensor

203 Each memory module slot has a IPMI sensor to detect when the memory module is
 204 present. The sensor is present in the Device SDR repository at all times.

DRAM-SLO-4.19 For each memory module slot FRU Device Locator Record there **shall** be a Presence Detect Compact Sensor Record with the *Entity Instance*(byte 10) field identical to the FRU Device Locator Record's *FRU Entity Instance* Field(byte 14).

DRAM-SLO-4.20 The memory module slot Presence Detect Compact Sensor Record and Memory Module Slot FRU Device Locator Record that have identical values for the Entity Instance **shall** be present in the same LUN ID's Device SDR.

DRAM-SLO-4.21 Each memory module slot Presence Detect Compact Sensor Record **shall** have the *Entity ID* field(byte 9) set to 8h.

DRAM-SLO-4.22 Each memory module slot Presence Detect Compact Sensor Record **shall** have the *Event/Reading Type Code* field set to 8h, Device Absent/Device Present.

DRAM-SLO-4.23 When an memory module is removed all Full and Compact Sensor records **shall** be removed from the Device SDR prior to the IPM controller setting the memory module slot's Presence Detect sensor state to 0h(Device Removed / Device Absent).

DRAM-SLO-4.24 When an memory module is inserted all it's Full and Compact Sensor records **shall** be inserted into the Device SDR prior to the IPM controller setting the memory module slots Presence Detect sensor state to 1h(Device Inserted / Device Present).

DRAM-SLO-4.25 The Compact Sensor Record defining a memory module slot Presence Detect sensor **shall not** be removed from the Device SDR Repository.

205 5 Memory Modules

206 This specification has no requirements on the interface between the IPM Controller
207 and the memory module. It may be proprietary. One method is an I²C interface
208 between the IPM Controller and a memory module slot. The I²C interface is defined
209 by the JEDEC C-21 DDR Thermal Sensor specification. It allows up to eight DDR
210 memory modules per I²C bus.

211 The I²C interface to each memory allows an IPM Controller to detect if a DDR3 or
212 DDR4 memory module is present in the slot. Configuration information and operating
213 status can be read from the memory module.

214 5.1 Module Identification

215 An IPM Controller maps each memory module's Serial Presence Detect (SPD) data
216 bytes to a different FRU ID's FRU Information area as a OCP defined SDR Multi Record.
217 An IPM Controller is not required to read the SPD data until it received an IPMI Read
218 FRU Info command for the FRU ID. Once the IPM Controller or the System Manager
219 has read the SPD data no changes are allowed to that data until the IPM Controller is
220 rebooted.

221 The format of the SPD data is not compatible between the DDR3 (DDR3 SPD
222 Appendix K) and DDR4 (DDR4 SPD Appendix L). They share a common format for
223 Byte 2 of the SPD data that differentiates between the types of memory. Note that
224 the DDR4, Appendix L is only present in the JEDEC Standard No. 21-C Release 23 and
225 later versions.

226 The the SPD data contain a Cyclical Redundancy Code (CRC) . The IPM Controller is
227 not required to validate that the CRC is correct.

228 5.1.1 DDR3 SPD

229 The DDR3 SPD specification documents a sequence 128 bytes on each DDR3 module
230 that identify the size, capabilities, vendor and serial number.

231 The thermal characteristics of the memory module are defined by JEDEC 21-C as:

- 232 • Normal temperature range, 0 to 85 degrees C.
- 233 • Extended temperature range, 0 to 95 degrees C.

234 This information is present in the SPD as field *SDRAM Thermal and Refresh*
235 *Options*(byte 31).

236 5.1.2 DDR4 SPD

237 The DDR4 SPD specification documents the of sequence 512 bytes on each DDR4
238 module that identify the size, capabilities, vendor and serial number.

239 The thermal characteristics of the memory module are defined by the hardware
240 vendor an present in the SPD as field *SDRAM Thermal and Refresh Options*(byte 8).

241 5.1.3 DRAM Multi Record Description

242 An IPM Controller maps each memory module's Serial Presence Detect data to a
243 single FRU's Multi Record area containing a DRAM Module Description Record.

244

Table 1. DRAM Module Description Record

Offset	Field Length	Field Name
0	1	<i>Record Type ID</i> . For all records defined in this specification a value of D0h (OEM) is used.
1	1	End of List/Version [7:7]- End of List. Set to one for the last record. [6:4]- Reserved. Write as 0h. [3:0]- Record Format Version. For this specification 0h.
2	1	Record Length
3	1	<i>Record Checksum</i> . The zero Checksum of the record.
4	1	<i>Header Checksum</i> . The zero Checksum of the header.
5	3	<i>Manufacturer ID</i> . The Private Enterprise number assigned to OCP. Write as 42623 (A67Fh) . Least significant byte first.
8	1	<i>OCP Record ID</i> . 04h
9	1	<i>Record Format Version</i> . [7:4] Reserved. Write as 0h. [3:0] Format Version ID. Use 0h to identify this table.
10	9+N	<i>DRAM Module Description</i> . The memory module Serial Presence Detect data formatted according to DDR3 SPD or DDR4 SPD specification. The size, N, is determined from the SPD data byte offset zero, bits [3:0].

DRAM-MOD-5.1 If a memory module is detected in a memory module slot the IPM Controller **shall** set the FRU ID's Common Header field *MultiRecord Area Starting Offset* to the starting offset of the FRU Multi record containing the DRAM Module Description

245 5.2 Temperature Sensor

246 The DDR3 and DDR4 SPD data contains a field indicating the presence of a
247 temperature sensor on the memory module. The sensor is optional for 85° C
248 modules and mandatory for 95° C modules. When the sensor is present this section
249 documents how an IPM Controller interacts with the sensor. The sensor allows each
250 DDR memory module to provide temperature readings that provide information on
251 the health and status of the hardware. If a server is implemented without Fan speed
252 sensors the rise in DDR temperatures is often the first indication that Fan is failing.

253 The DDR Thermal Sensor specification defines the sensor thresholds and how the
254 thermal sensor is read.

255 When the memory module is detected in a slot the IPM Controller reads the memory
256 modules SPD data to determine if the module contains a temperature sensor. If a
257 temperature sensor is present the IPM Controller copies the Entity Instance Number
258 from the FRU Device Locator record and creates temperature sensor thresholds to
259 assemble the temperature sensors Full Sensor Record. Then the Full sensor record is
260 inserted into the same LUN ID's Device SDR repository where the FRU Device Locator
261 Record was found.

- DRAM-MOD-5.2 If the IPM Controller detects that a memory module implements a temperature sensor the IPMI Controller **shall** create a Full Sensor Record with the *Entity ID* field set to 8h(memory module) in the Device SDR Repository of the LUN ID field(byte 7) found in the Full Sensor Record.
- DRAM-MOD-5.3 The memory module temperature Full Sensor SDR **shall** have the *Sensor Type* field set to 1h(Temperature),
- DRAM-MOD-5.4 The DDR memory module temperature Full Sensor SDR **shall** shall have the upper non-critical threshold from the data in DDR Thermal Sensor, Section 6.5.1 Alarm Temperature Upper Boundary Register.
- DRAM-MOD-5.5 The DDR memory module temperature Full Sensor SDR **shall** have the lower non-critical threshold from the data in DDR Thermal Sensor, Section 6.5.2 Alarm Temperature Lower Boundary Register.
- DRAM-MOD-5.6 The DDR memory module temperature Full Sensor SDR **shall** have the upper critical threshold from the data in DDR Thermal Sensor, Section 6.5.3 Critical Temperature Register.
- DRAM-MOD-5.7 The memory module temperature Full Sensor SDR **shall** have the *Entity Instance* field(byte 10) set to a value found in a memory module slot's FRU Device Locator Record's *FRU Entity Instance* Field.

262 6 ID Assignment

263

Table 2: FRU Information Record ID Assignments

FRU Record Name	Table Number	Record ID	Chassis Manager	Node Manager
DRAM Module Description Record	1	4h	Yes	Yes

264

The OEM values for the IPM 2.0, Table 43-1, IPMB/I2C Device Type Codes.

265

Table 3: IPMB/I2C Device Type Codes

Sensor Type Code	Sensor Name
C0h	DDR3 Memory Slot
C1h	DDR4 Memory Slot